Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

NCP580

Ultra-Fast, Low Noise 120 mA CMOS LDO Regulator with Enable

The NCP580 series of low dropout regulators are designed for portable battery powered applications which require precise output voltage accuracy, low quiescent current, and high ripple rejection. These devices feature an enable function which lowers current consumption significantly and are offered in the small SC−82AB package.

A 2.2 μF ceramic capacitor or higher is the recommended value to be used with these devices on the output pin.

Features

- Ultra−Low Dropout Voltage of 150 mV at 100 mA
- Low Output Noise of 30 μVrms without Noise Reduction Cap
- Excellent Line Regulation of 0.02%/V
- Excellent Load Regulation of 12 mV
- High Output Voltage Accuracy of ± 1.5%
- Low Iq Current of 90 μA
- Very Low Shutdown Current of 0.1 μA
- Excellent Power Supply Rejection Ratio of 70 dB at f = 1.0 kHz
- Wide Output Voltage Range of 1.5 V to 3.3 V
- Fold Back Protection Circuit
- Fast Dynamic Performance
- Low Temperature Drift Coefficient on the Output Voltage of ± 100 ppm/°C
- Input Voltage up to 6.5 V
- These are Pb−Free Devices

Typical Applications

- Portable Equipment
- Hand−Held Instrumentation
- Camcorders and Cameras

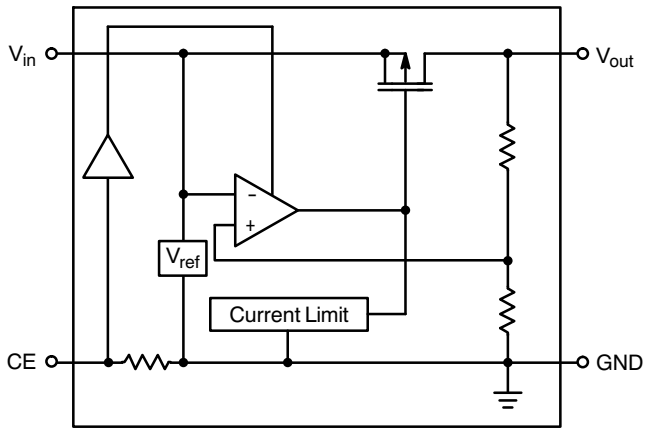
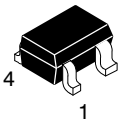


Figure 1. Simplified Block Diagram

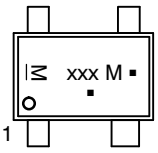
ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM



SC−82AB
SQ SUFFIX
CASE 419C



xxx = Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

PIN FUNCTION DESCRIPTION

Pin	Symbol	Description
1	V_{out}	Regulated output voltage.
2	GND	Power supply ground.
3	CE	Chip enable pin.
4	V_{in}	Power supply input voltage.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage	V_{in}	6.5	V
Input Voltage (CE Pin)	V_{CE}	−0.3 to V_{in} +0.3	V
Output Voltage	V_{out}	−0.3 to V_{in} +0.3	V
Output Current	I_{out}	140	mA
Power Dissipation	P_D	150	mW
ESD Capability, Human Body Model, C = 100 pF, R = 1.5 kΩ	ESD_{HBM}	1500	V
ESD Capability, Machine Model, C = 200 pF, R = 0 Ω	ESD_{MM}	150	V
Operating Ambient Temperature Range	T_A	−40 to +85	°C
Maximum Junction Temperature	$T_{J(max)}$	125	°C
Storage Temperature Range	T_{stg}	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS (V_{in} = V_{out} + 1.0 V, T_A = 25°C, unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
Input Voltage	V_{in}	2.2	–	6.0	V
Output Voltage (I_{out} = 1.0 mA to 30 mA)	V_{out}	V_{out} X 0.985	–	V_{out} X 1.015	V
Line Regulation (I_{out} = 30 mA) (V_{out} + 0.5 V ≤ V_{in} ≤ 6.0 V) (V_{out} = 1.5 V, 2.2 V ≤ V_{in} ≤ 6.0 V)	Reg_{line}	–	0.02	0.10	%/V
Load Regulation (I_{out} = 1.0 mA to 120 mA)	Reg_{load}	–	12	40	mV
Dropout Voltage (I_{out} = 120 mA) V_{out} = 1.5 V V_{out} = 1.8 V V_{out} = 2.5 V 2.8 V ≤ V_{out} ≤ 3.3 V	V_{DO}	 – – – –	 0.36 0.28 0.24 0.18	 0.70 0.40 0.35 0.28	V
Quiescent Current (I_{out} = 0 mA)	Iq	–	90	160	μA
Output Current	I_{out}	120	–	–	mA
Shutdown Current (V_{in} = V_{CE})	I_{SD}		0.1	1.0	μA
Output Short Circuit Current (V_{out} = 0)	I_{lim}	–	40	–	mA
Ripple Rejection (I_{out} = 30 mA) f = 1.0 kHz (V_{out} = 1.5 V, V_{in} − V_{out} = 1.2 V) (V_{out} ≥ 2.5 V, V_{in} − V_{out} = 1.0 V)	RR	 – –	 75 70	 – –	dB
Enable Input Threshold Voltage − High − Low	Vth_{enh} Vth_{enl}	1.5 0	– –	V_{in} 0.3	V
Output Noise Voltage (Bandwidth = 10 Hz to 100 kHz)	V_n	–	30	–	μVrms
Output Voltage Temperature Coefficient (I_{out} = 30 mA, −40°C ≤ T_A ≤ 85°C)	$\Delta V_{out}/\Delta T$	–	±100	–	ppm/°C

TYPICAL CHARACTERISTICS

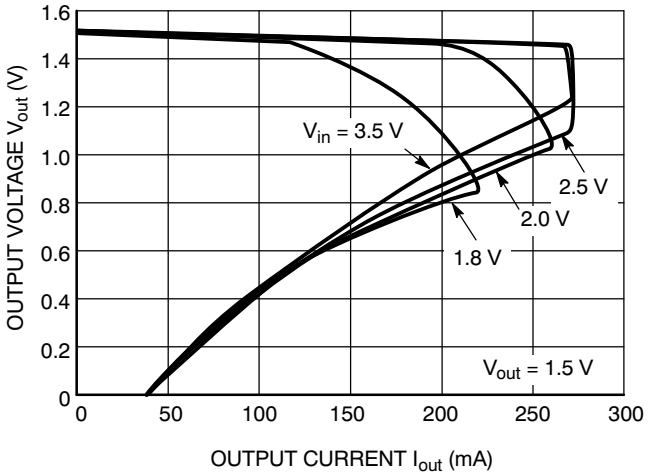


Figure 2. Output Voltage vs. Output Current

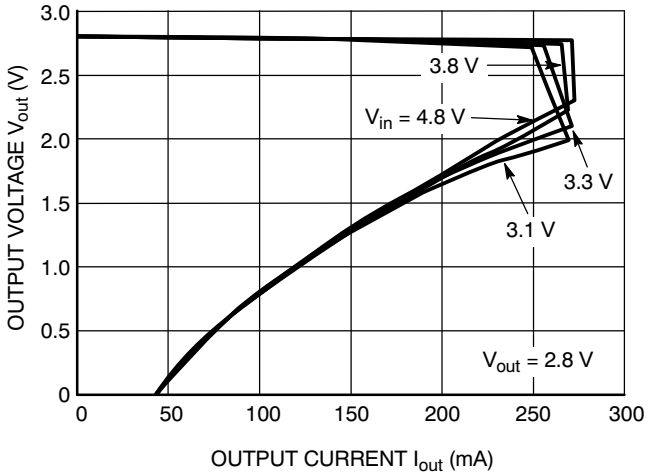


Figure 3. Output Voltage vs. Output Current

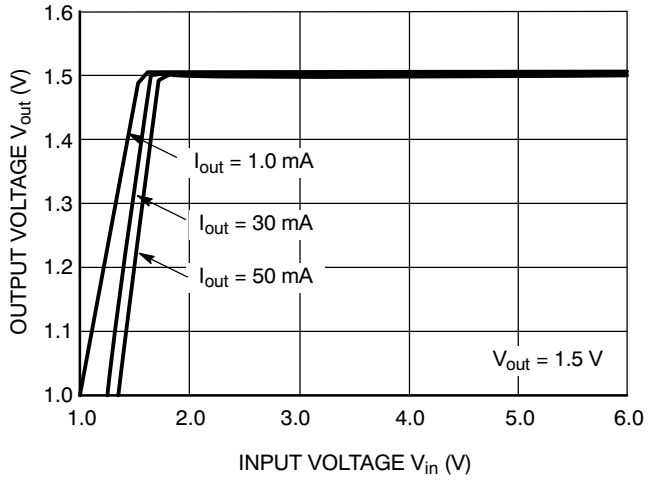


Figure 4. Output Voltage vs. Input Voltage

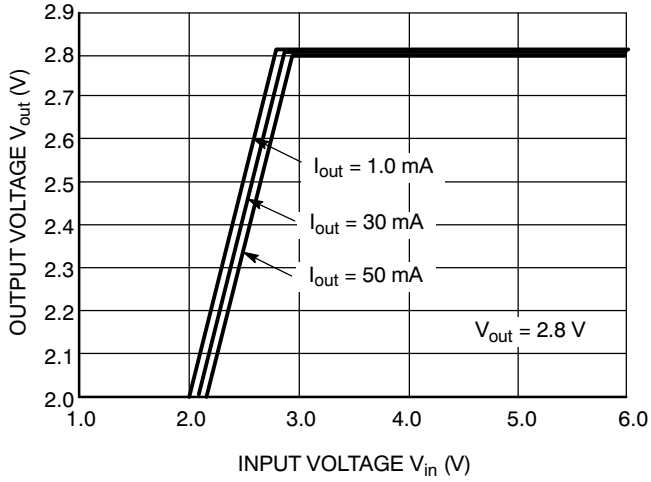


Figure 5. Output Voltage vs. Input Voltage

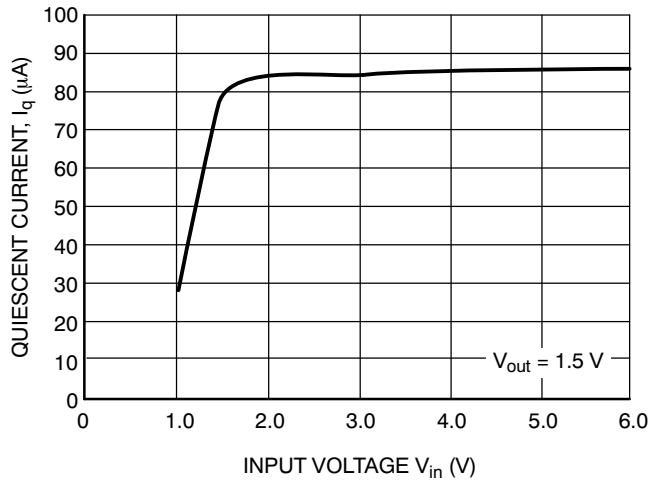


Figure 6. Quiescent Current vs. Input Voltage

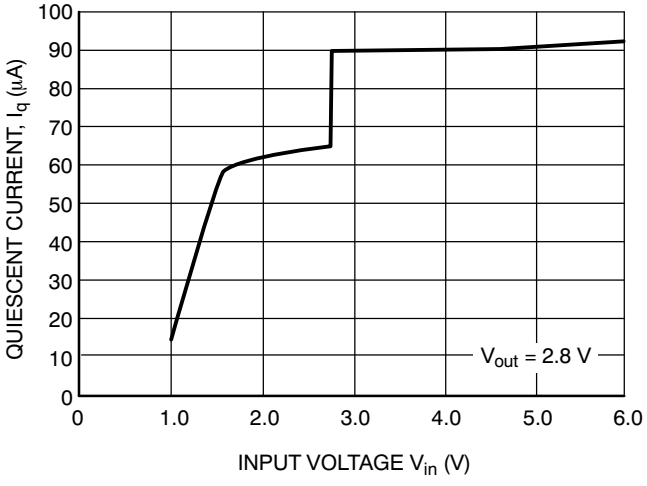


Figure 7. Quiescent Current vs. Input Voltage

TYPICAL CHARACTERISTICS

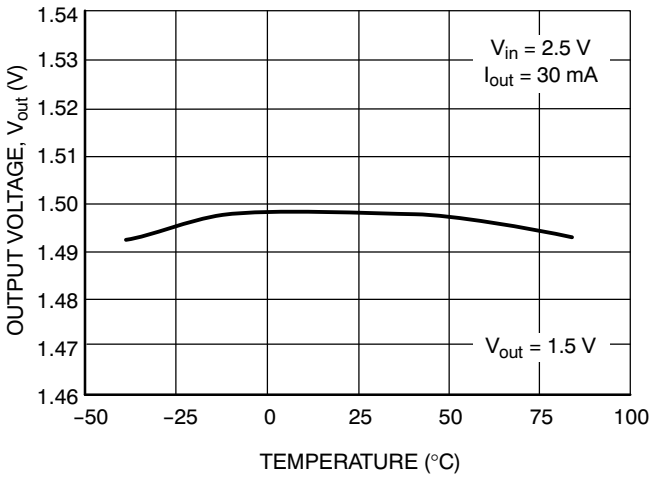


Figure 8. Output Voltage vs. Temperature

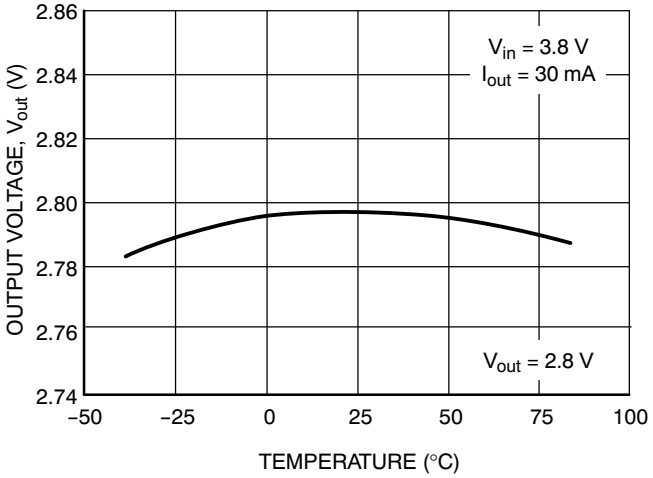


Figure 9. Output Voltage vs. Temperature

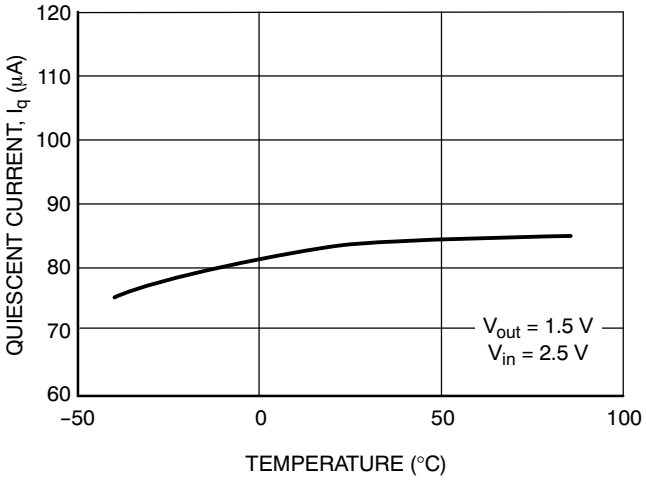


Figure 10. Quiescent Current vs. Temperature

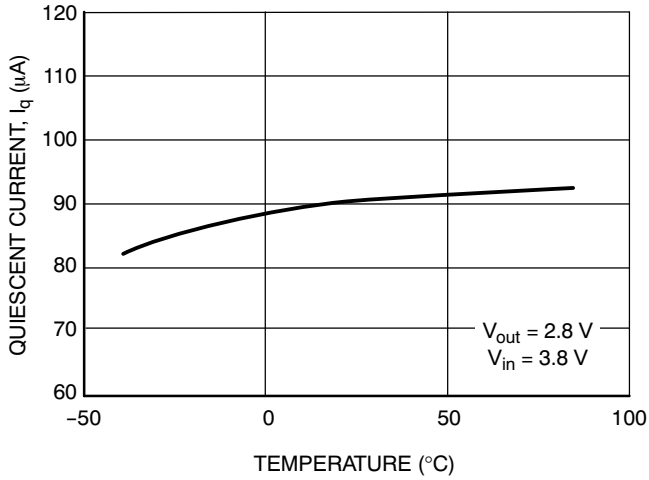


Figure 11. Quiescent Current vs. Temperature

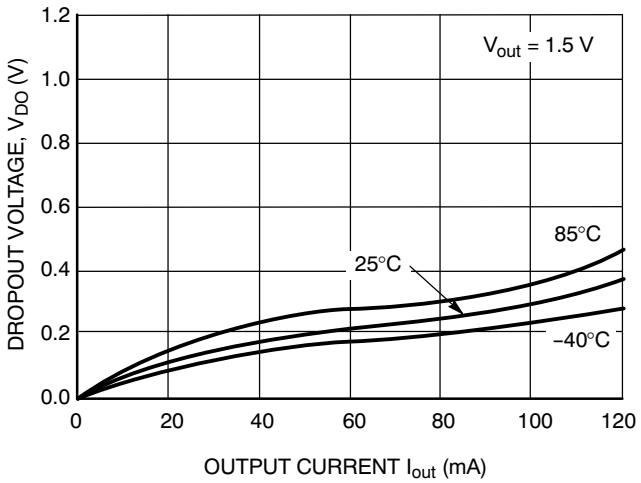


Figure 12. Dropout Voltage vs. Output Current

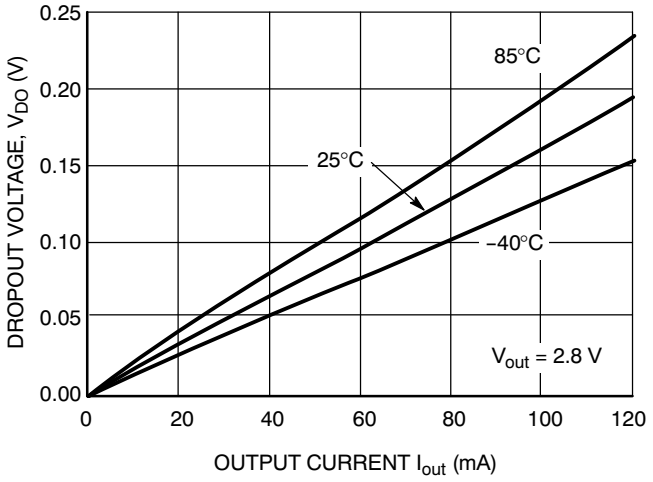


Figure 13. Dropout Voltage vs. Output Current

TYPICAL CHARACTERISTICS

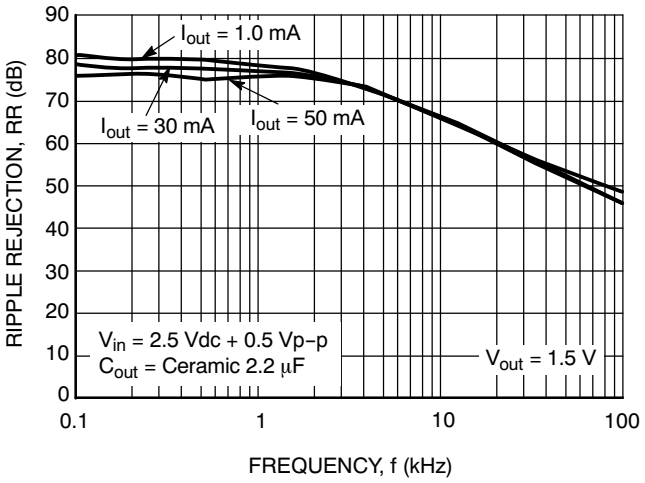


Figure 14. Ripple Rejection vs. Frequency

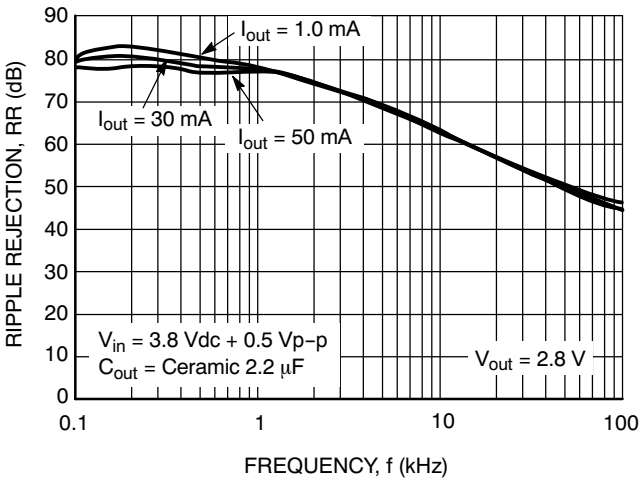


Figure 15. Ripple Rejection vs. Frequency

TYPICAL CHARACTERISTICS

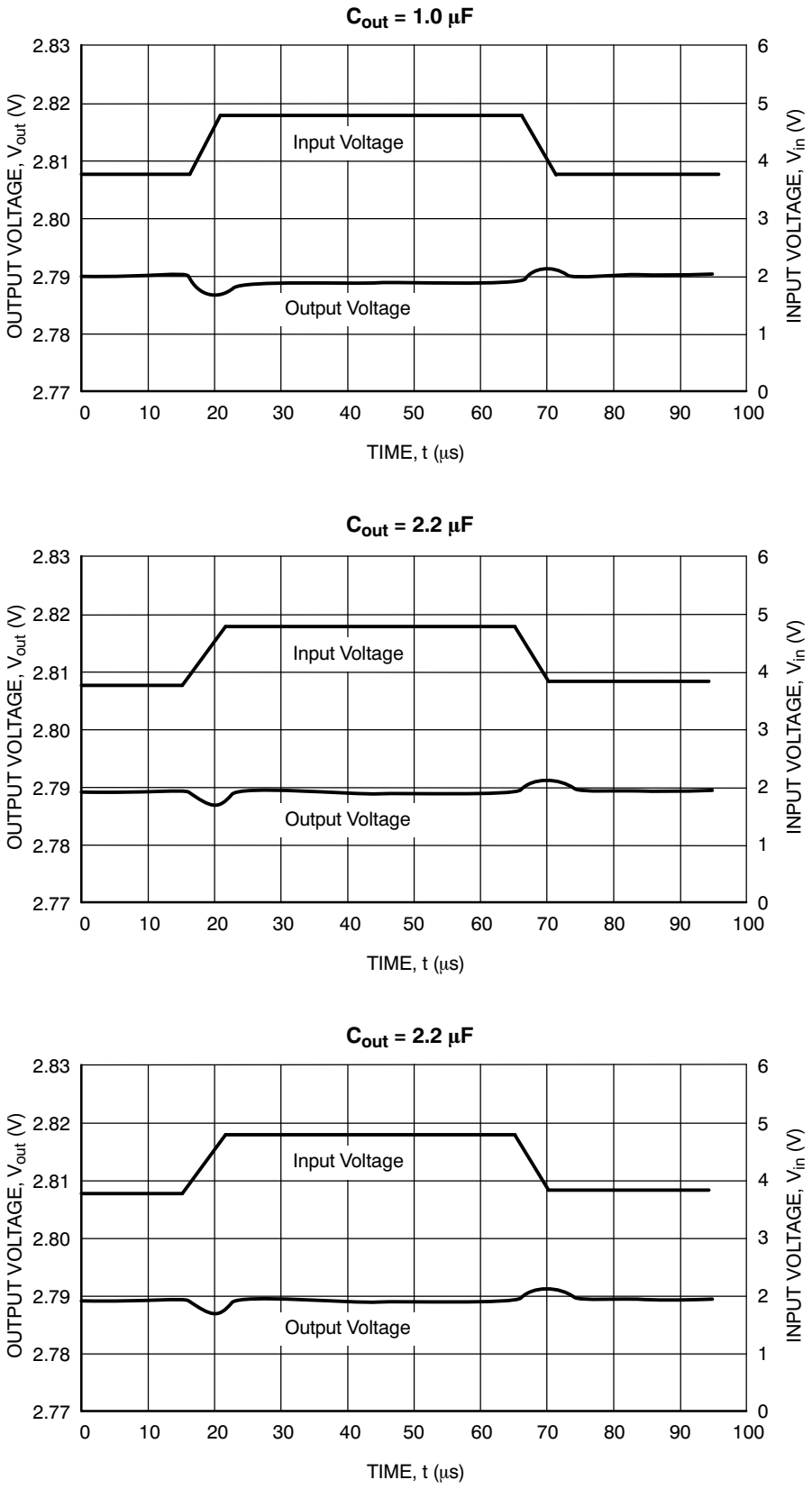


Figure 16. Input Transient Response
(V_{in} = 3.8 V to 4.8 V, I_{out} = 30 mA, tr = tf = 5.0 μs, V_{out} = 2.8 V)

TYPICAL CHARACTERISTICS

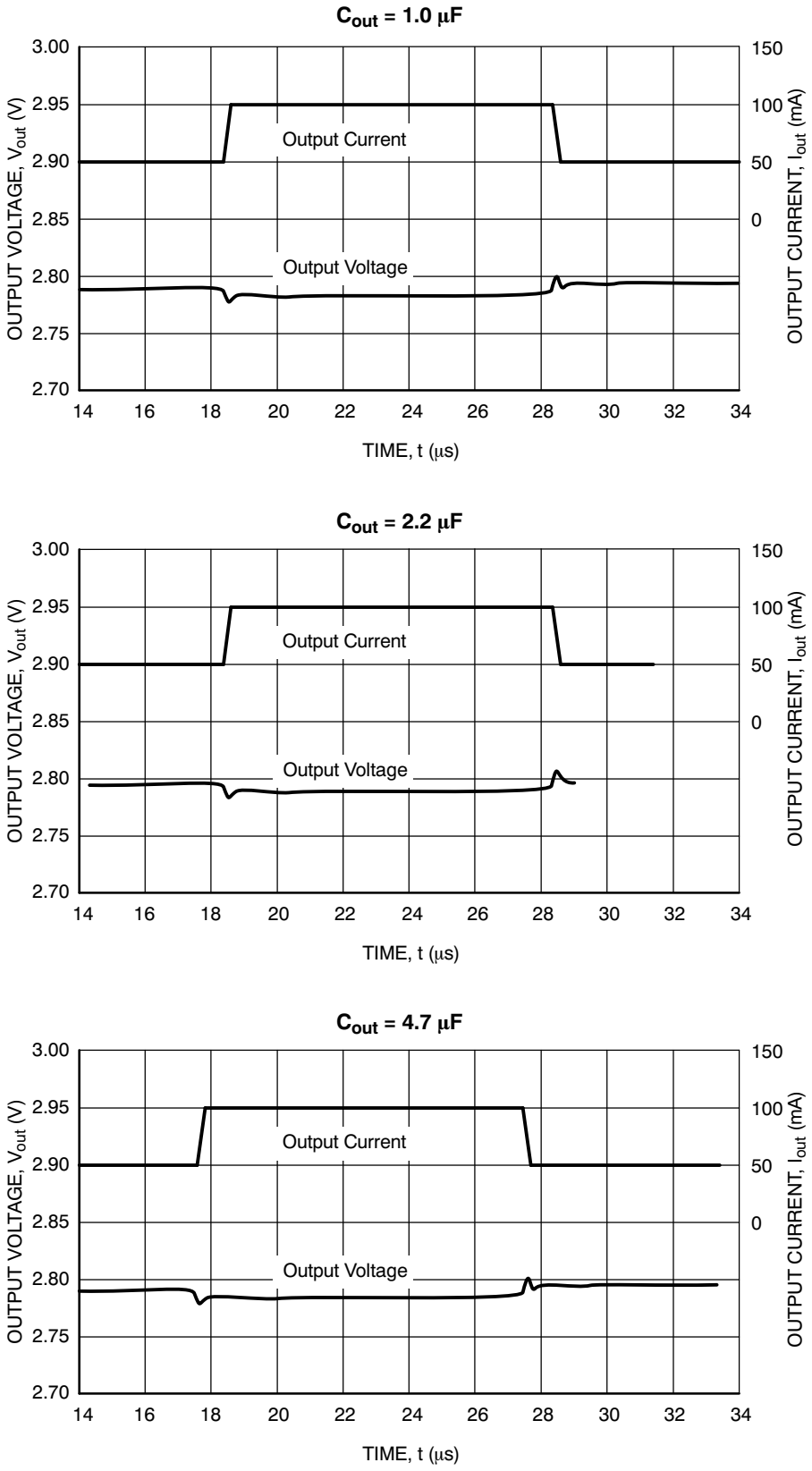


Figure 17. Load Transient Response
(V_{in} = 3.8 V, I_{out} = 50 mA to 100 mA, tr = tf = 5.0 μs, C_{in} = 1.0 μF, V_{out} = 2.8 V)

APPLICATION INFORMATION

Input Decoupling

A 1.0 μF ceramic capacitor is the recommended value to be connected between V_{in} and GND. For PCB layout considerations, the traces of V_{in} and GND should be sufficiently wide in order to minimize noise and prevent unstable operation.

Output Decoupling

It is best to use a 2.2 μF or higher capacitor value on the V_{out} pin. For better performance, select a capacitor with low Equivalent Series Resistance (ESR). For PCB layout considerations, place the output capacitor close to the output pin and keep the leads short as possible.

ORDERING INFORMATION

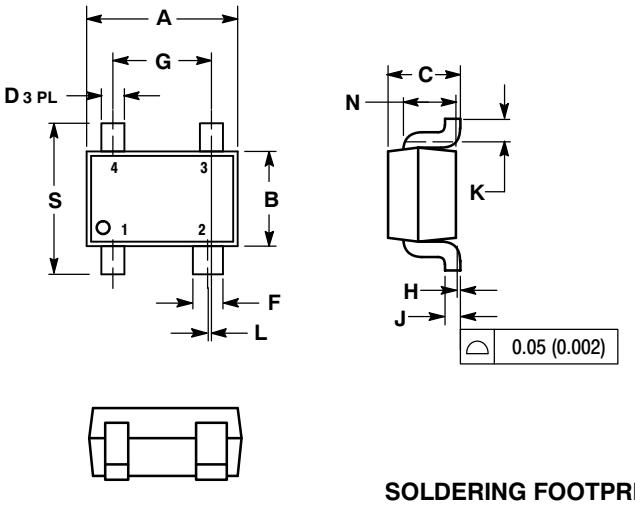
Device	Output Type / Features	Nominal Output Voltage	Marking	Package	Shipping†
NCP580SQ15T1G	Active High	1.5	AF	SC−82AB (Pb−Free)	3000 / Tape & Reel
NCP580SQ18T1G	Active High	1.8	AJ	SC−82AB (Pb−Free)	3000 / Tape & Reel
NCP580SQ25T1G	Active High	2.5	BF	SC−82AB (Pb−Free)	3000 / Tape & Reel
NCP580SQ28T1G	Active High	2.8	BJ	SC−82AB (Pb−Free)	3000 / Tape & Reel
NCP580SQ30T1G	Active High	3.0	CA	SC−82AB (Pb−Free)	3000 / Tape & Reel
NCP580SQ33T1G	Active High	3.3	CD	SC−82AB (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Other voltages are available. Consult your ON Semiconductor representative.

PACKAGE DIMENSIONS

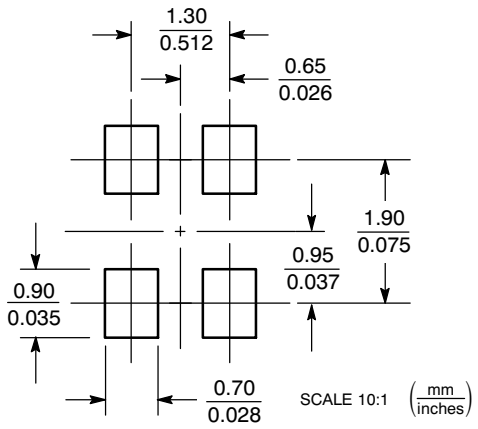
SC−82AB
SQ SUFFIX
CASE 419C−02
ISSUE E



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. 419C−01 OBSOLETE. NEW STANDARD IS 419C−02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	1.8	2.2	0.071	0.087
B	1.15	1.35	0.045	0.053
C	0.8	1.1	0.031	0.043
D	0.2	0.4	0.008	0.016
F	0.3	0.5	0.012	0.020
G	1.1	1.5	0.043	0.059
H	0.0	0.1	0.000	0.004
J	0.10	0.26	0.004	0.010
K	0.1	−−−	0.004	−−−
L	0.05 BSC		0.002 BSC	
N	0.2 REF		0.008 REF	
S	1.8	2.4	0.07	0.09

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
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For additional information, please contact your loca
Sales Representative